

In the Claims

Claims 1-31 (Canceled)

32. (New) A tableting machine for compressing tablets, comprising:
a die formed with a bore to receive granules, said die being mounted on a die table,
an upper punch disposed above the die bore and being downwardly moveable into the die bore
to compress the granules into a tablet,
a lower punch disposed under the die bore and being upwardly moveable into the die bore to
eject the compressed tablet from the die bore,
wherein the upper punch, the lower punch and the die comprise a high-silicon steel, and
wherein the upper punch, the lower punch and the die have surfaces in contact with the
granules, which surfaces are carburized.

33. (New) The tableting machine according to claim 32, wherein the high-silicon steel
consists essentially of about 0 to 0.08% by weight C, about 3.5 to 6% by weight Si, about 0 to 5%
by weight Mn, about 3 to 9% by weight Ni, about 6 to 15% by weight Cr, and the balance being Fe,
the total amount of Ni and Mn being about 2-fold the amount of Si, the amount of Cr being about
2.5-fold the amount of Si, and the A_3 transformation temperature is not higher than about 750°C.

34. (New) The tableting machine according to claim 32, wherein the high-silicon steel
consists essentially of about 0 to 0.05% by weight C, about 3.5 to 6% by weight Si, about 2 to 6%
by weight Mn, about 1 to 4% by weight Ni, about 8 to 16% by weight Cr, about 0.3 to 3% by weight
Mo, about 1 to 4% by weight Cu, and the balance being Fe, the total amount of Ni, Mn and Cu being
about 2.5-fold the amount of Si, the amount of Cr being about 3-fold the amount of Si, and the A_3
transformation temperature is not higher than about 750°C.

35. (New) The tableting machine according to claim 32, wherein the high-silicon steel
consists essentially of about 0 to 0.1% by weight C, about 4 to 9% by weight Si, about 0 to 3% by

weight Mn, about 6 to 18% by weight Ni, about 16 to 25% by weight Cr, about 0 to 3% by weight Mo, about 0 to 3% by weight Co and/or about 0 to 2% by weight Cu, and the balance being Fe, the total amount of Ni and Mn being about 2-fold the amount of Si, the amount of Cr being about 3.5-fold the amount of Si, and the A_3 transformation temperature is not higher than about 750°C.

36. (New) The tableting machine according to claim 32, wherein high-silicon steel consists essentially of about 0 to 0.05% by weight C, about 4 to 7% by weight Si, about 0 to 3% by weight Mn, about 6 to 16% by weight Ni, about 12 to 20% by weight Cr, about 0 to 4% by weight V, about 0 to 4% by weight Mo, about 0 to 4% by weight W, about 0 to 1% by weight Ti, about 0 to 1% by weight Al and/or about 0 to 1% by weight Co, about 0 to 1% by weight Cu, and the balance being Fe, the total amount of Ni and Mn being about 2-fold the amount of Si, the amount of Cr being about 3.5-fold the amount of Si, and the A_3 transformation temperature is not higher than about 750°C.

37. (New) The tableting machine according to claim 32, wherein high-silicon steel consists essentially of about 0 to 0.05% by weight C, about 2 to 4% by weight Si, about 0 to 2% by weight Mn, about 5 to 10% by weight Ni, about 8 to 13% by weight Cr, about 0.2 to 1% by weight Mo, about 0.5 to 3% by weight Cu, the balance being Fe, and the sum of 2 times the amount of Cr and the amount of Si is about 20-30% by weight of the whole amount.

38. (New) The tableting machine according to claim 32, wherein the carburized surfaces of the upper punch, the lower punch and the die comprise a concentrated carbon layer having a thickness in a range of 5 to 100 microns.

39. (New) A method for manufacturing tablets, which comprises compressing granules provided in the die bore of the tableting machine defined in claim 32 into tablets, wherein the granules contain a corrosive substance or an adhesive substance.

40. (New) The method according to claim 39, wherein the corrosive substance is an acidic substance.

41. (New) The method according to claim 39, wherein the adhesive substance is one or more substance(s) selected from a group consisting of an adhesive pharmacologically active substance, an adhesive low-melting substance and an adhesive excipient.

42. (New) The method according to claim 39, wherein the corrosive substance or adhesive substance is contained in the granules in an amount of 0.001 to 99.5% by weight.

43. (New) The method according to claim 39, wherein the corrosive substance is contained in the granules in an amount of 0.1 to 50 % by weight.

44. (New) The method according to claim 39, wherein the adhesive substance is contained in the granules in an amount of 0.1 to 90 % by weight.

45. (New) A tablet which is manufactured according to the method of claim 39.